

- Surface device type mounting
- Moisture sensitivity level 1
- Matte Tin(Sn) lead finish with Nickel(Ni) underplate
- Packing code with suffix "G" means green compound (halogen-free)



SOT-23

MECHANICAL DATA

- Case: SOT- 23, molded plastic
- Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed: 260°C/10s
- Weight: 0.008g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)			
PARAMETER		SYMBOL	VALUE
Power Dissipation		P _D	200
Repetitive Peak Reverse Voltage		V _{RRM}	40
Reverse Voltage		V _R	40
Repetitive Peak Forward Current		I _{FRM}	200
Mean Forward Current		I _O	200
Non-Repetitive Peak Forward Surge Current (Note 1)		I _{FSM}	0.6
Thermal Resistance (Junction to Ambient) (Note 2)		R _{θJA}	357
Junction and Storage Temperature Range		T _J , T _{STG}	-65 to +125

PARAMETER		SYMBOL	MIN	MAX
Reverse Breakdown Voltage	I _R =10μA	V _(BR)	40	-
	I _F =1mA			
	I _F =10mA			
	I _F =40mA			
Forward Voltage		V _F	-	0.38
			-	0.50
			-	1.00
			-	
Reverse Leakage Current	V _R =30V	I _R	-	0.2
Junction Capacitance	V _R =1V, f=1.0MHz	C _J	-	5.0
Reverse Recovery Time	I _F =I _R =10mA, R _L =100Ω, I _{RR} =1mA	t _{rr}	-	5.0

Notes : 1. Test Condition : 8.3ms single half sine-wave superimposed on rated load

Notes : 2. Valid provided that electrodes are kept at ambient temperature

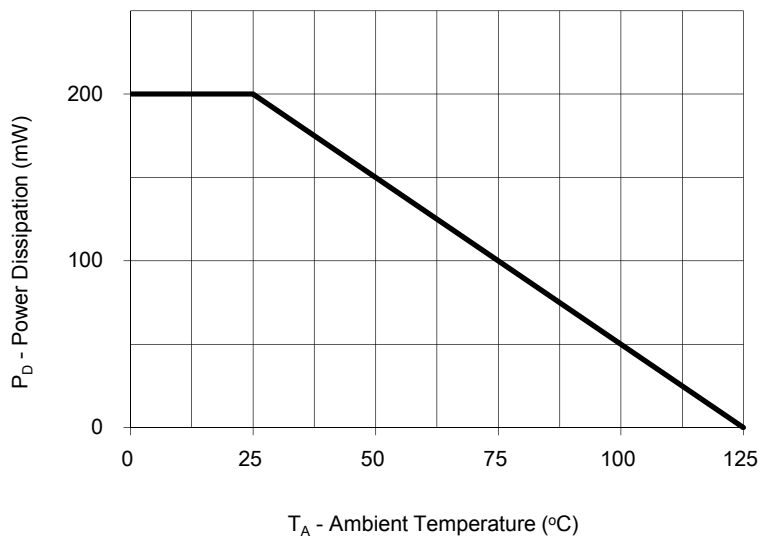


Fig. 3 Typical Forward Characteristics

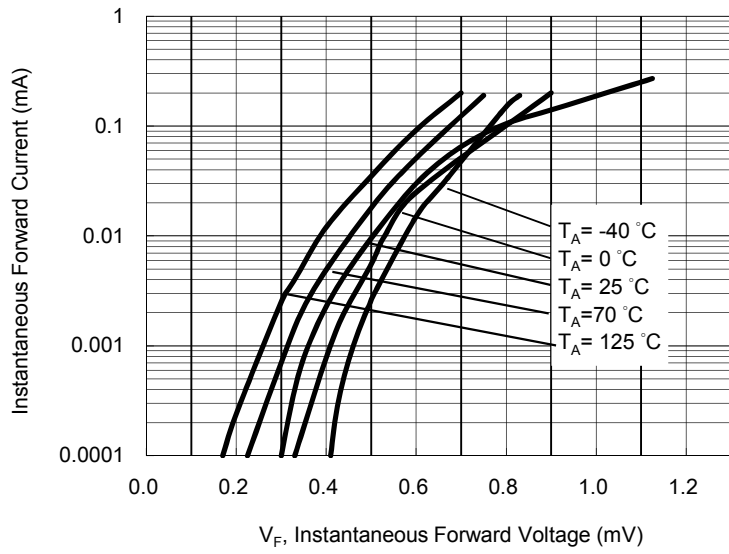


Fig. 5 Typical Total Capacitance VS. Reverse Voltage

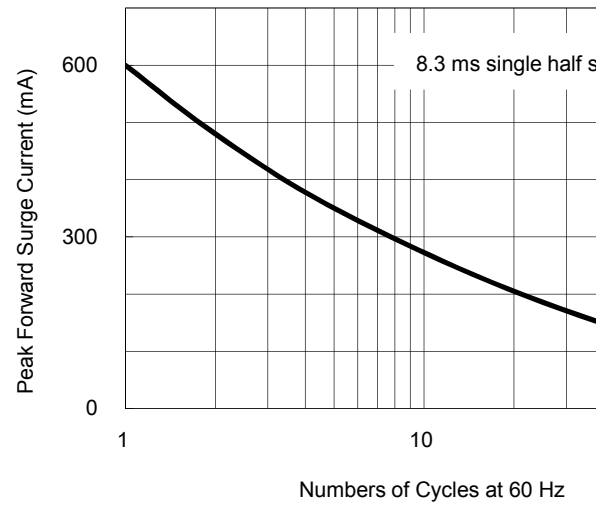
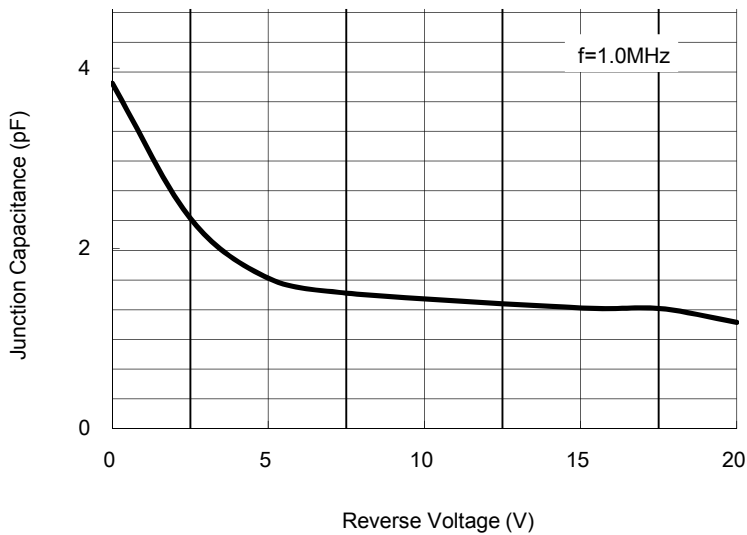


Fig. 4 Typical Reverse Characteristics

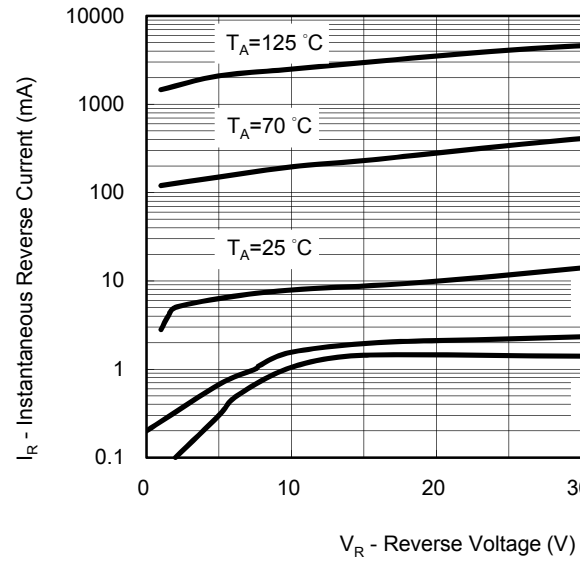
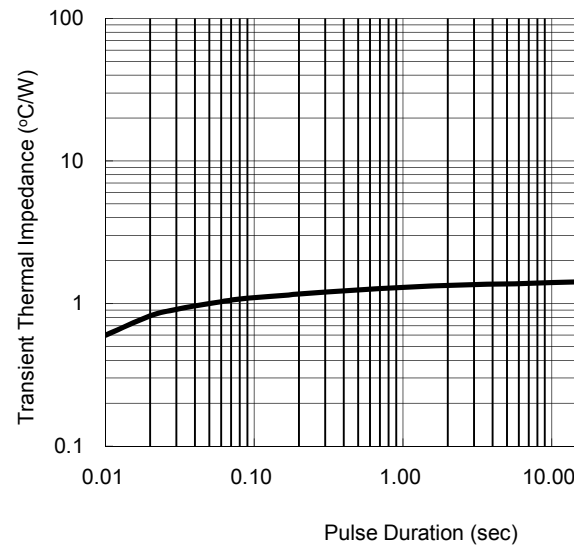


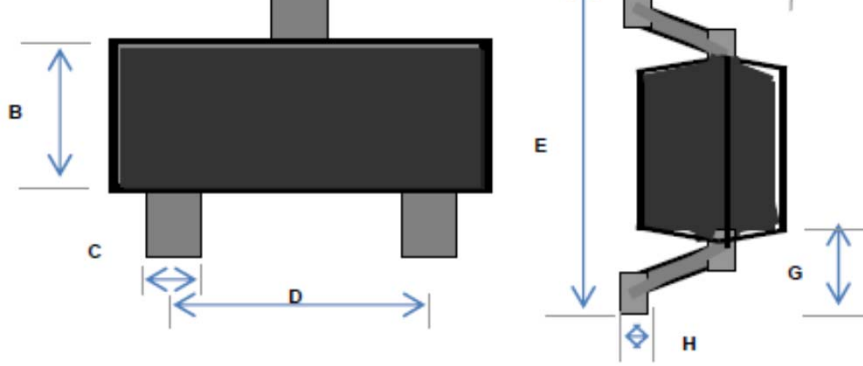
Fig. 6 Typical Transient Thermal Impedance



BAS40-05	-xx	RF	G	SO1-23	3K / 7" Reel
BAS40-06					

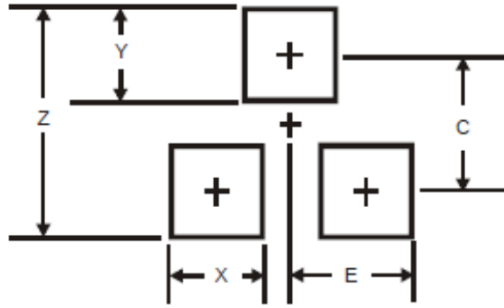
Note 1: Part No. Suffix „-xx “ would be used for special requirement

EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DE
BAS40 RF	BAS40		RF		Multip
BAS40 RFG	BAS40		RF	G	Multip Gre
BAS40-D0 RFG	BAS40	-D0	RF	G	Defin Gre



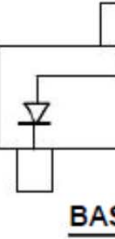
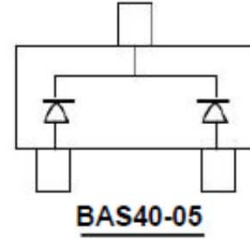
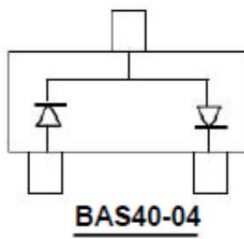
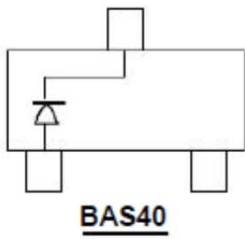
A	2.70	3.10	0.1
B	1.10	1.50	0.0
C	0.30	0.51	0.0
D	1.78	2.04	0.0
E	2.10	2.64	0.0
F	0.89	1.30	0.0
G	0.55 REF		
H	0.10 REF		

SUGGEST PAD LAYOUT



DIM.	Unit(mm)	
	Typ.	
Z	2.8	
X	0.7	
Y	0.9	
C	1.9	
E	1.0	

PIN CONFIGURATION



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